





(0,635 mm) .025"

QTS SERIES

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTS

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze Plating: Au or Sn over 50μ" (1,27 μm) Ni Current Rating: Contact: 1.8 A per pin (1 pin powered per row) Ground Plane:

Ground Plane:
23.1 A per ground plane
(1 ground plane powered)
Operating Temp:
-55°C to +125°C
Voltage Rating: 285 VAC
Max Cycles: 100
RoHS Compliant: Yes

Processing: Lead-Free Solderable: Yes SMT Lead Coplanarity: (0,10 mm) .004" max (025-075) Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height (Caution: Some automatic placement/ inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30μ" (0,76 μm) Gold
- · Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount Contact Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.



Cable Mates:

QTS/QSS

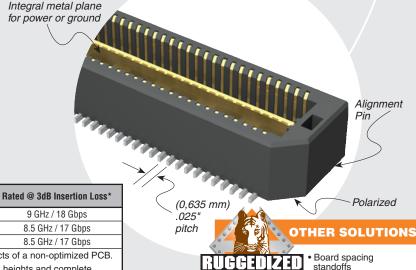
5 mm Stack Height

Single-Ended Signaling

Differential Pair Signaling

Differential Pair Signaling





Performance data includes effects of a non-optimized PCB. Performance data for other stack heights and complete test data available at www.samtec.com?QTS or contact sig@samtec.com **LEAD** NO. OF POSITIONS QTS

PER ROW

Type

–D

–D

-DP

-025, -050, -075 (50 total positions per bank)

(20,00) .7875

← (0,635) .025

(5,97)

235

Specify LEAD STYLE from chart.

(7,11)

STYLE

-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

PLATING

OPTION

= 10μ" (0,25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

SAMTEC

-C*

= Electro-Polished Selective 50μ" (1,27 μm) min Au over 150μ" (3,81 μm) Ni on Signal Pins in contact area, 10μ" (0,25 μm) min Au over 50μ" (1,27 μm) Ni on Ground Plane in contact area, Matte Tin over 50μ" (1,27 μm) min Ni on all solder tails



| STACK HEIGHTS | | |
|---|-------------|-----------------|
| LEAD STYLE | Α | MATED HEIGHT |
| -01 | (4,27) .168 | (5,00) .197 |
| -02 | (7,26) .286 | (8,00) .315 |
| Processing conditions will affect mated height. | | |

standoffs

(See SO Series)

OTHER

OPTION

–K

= (7,00 mm)

.275" DIA

Polyimide film Pick & Place Pad

-TR

= Tape & Reel

| (0,76) |
|--------------|
| |
| (0,89) |
| .035 → ← ' |
| DIA |

(0,20) .008 →

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